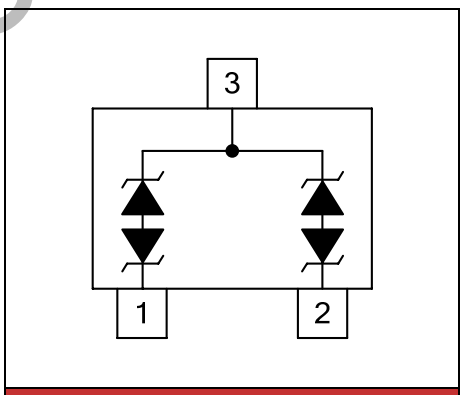
Electrostatic Discharged Protection Devices (ESD) Data Sheet

Description

Brightking's SDT23C24L02 component is designed to protect sensitive electronics from damage or latch-up due to ESD and other voltage induced transient events. It is designed for use in applications where board space is at a premium. The device will protect up to two lines. It is bidirectional devices and may be used on lines where the signal polarities are above ground. TVS diodes are solid state device designed specifically for transient suppression. It feature large cross-sectional area junctions for conduction high transient currents. It offer desirable characteristics for board level protection including fast response time, low and clamping voltage, and no device degradation.The device may be used to meet the immunity requirements of IEC61000-4-2, level 4. The size SOT-23 package makes them ideal for use in portable electronics such as RS-422 I/Os, RS-232 I/Os, notebook computers, and servers.

Features

- IEC61000-4-2 ESD 15KV Air, 8KV contact compliance
- SOT-23 surface mount package
- Protects bidirectional two I/O lines
- Peak power dissipation of 350W under 8/20μs waveform
- Working voltage: 24V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270℃
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: C24



Pin Configuration

Applications

- RS-232 and RS-422 data lines
- Microprocessor based equipment
- LAN/WAN equipment
- Desktops PC and serves
- Notebook, Laptop and Palmtop computers
- Set Top Box
- Peripherals
- Serial and Parallel ports

Maximum Ratings

Rating	Symbol	Value	Unit
Peak pulse power (tp=8/20μs waveform)	P_{PP}	350	W
ESD voltage (Contact discharge)	V_{ESD}	±8	kV
ESD voltage (Air discharge)		±15	
Storage & operating temperature range	T_{STG} ,T_J	-55~+150	℃

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Electrical Characteristics (T_J=25℃)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V_{RWM}				24	V
Reverse breakdown voltage	V_{BR}	I_{BR}=1mA	26.7			V
Reverse leakage current	I_R	V_R=24V Each I/O pin			1	μA
Clamping voltage (tp=8/20μs)	V_C	I_{PP}=1A			43	V
Clamping voltage (tp=8/20μs)	V_C	I_{PP}=5A			52	V
Off state junction capacitance	C_J	0Vdc,f=1MHz Between I/O pins and GND		40		pF

Typical Characteristics Curves

Figure 1. Power Derating Curve

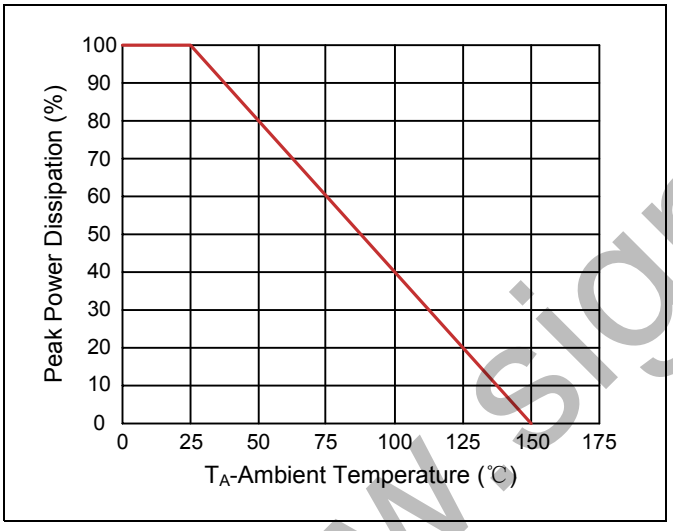


Figure 2. Pulse Waveforms

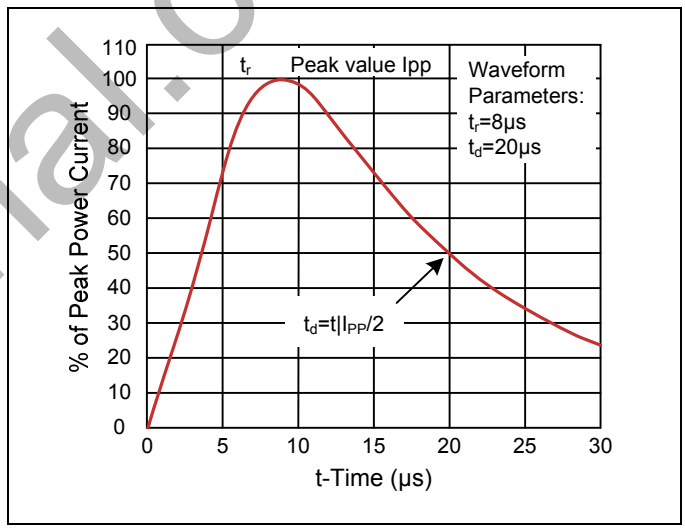


Figure 3. Non-Repetitive Peak Pulse vs. Pulse Time

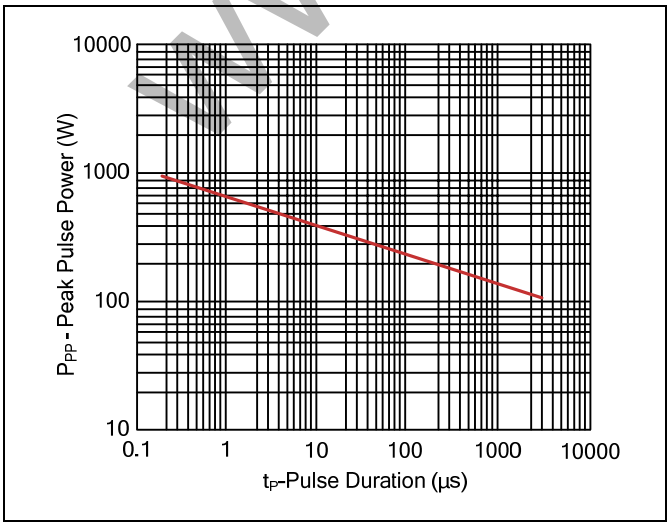
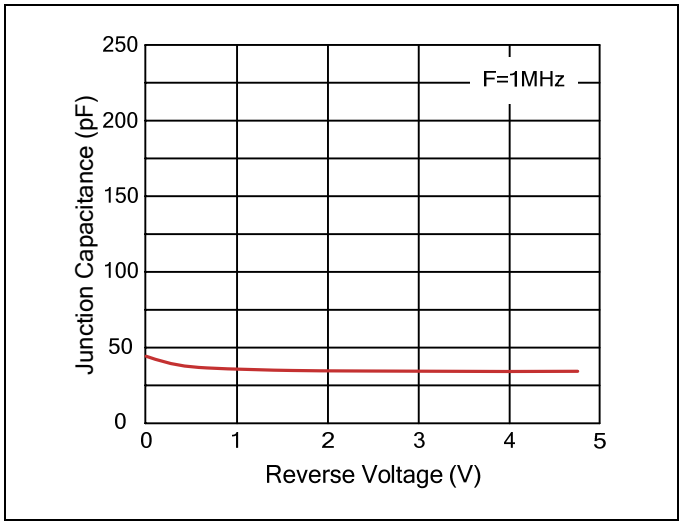


Figure 4. Normalized Capacitance vs. Reverse Voltage



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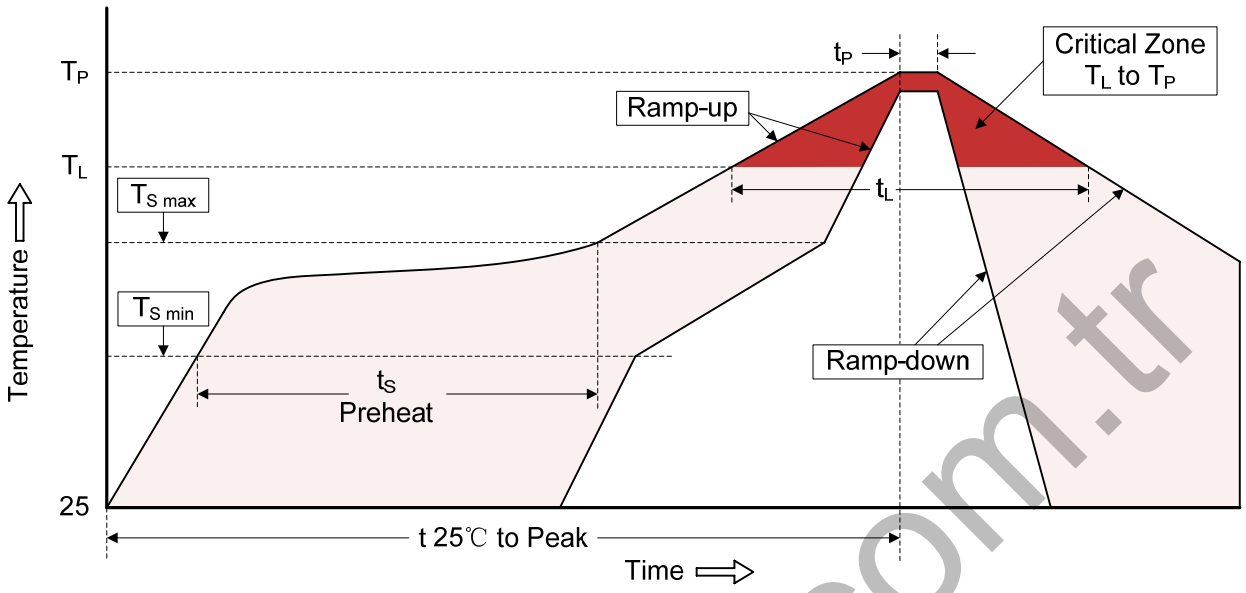
Recommended Soldering Conditions

Reflow Soldering



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3℃/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (ts)	 150℃ 200℃ 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	 3℃/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	 217℃ 60-150 seconds
Peak Temperature (T_P)	260℃
Time within 5℃ of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8 minutes max.

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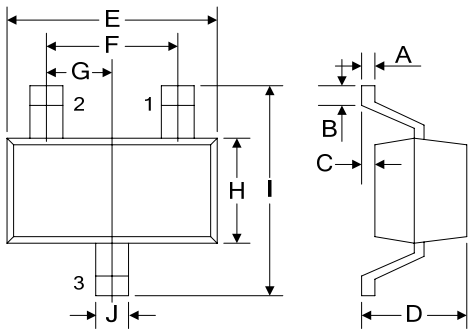
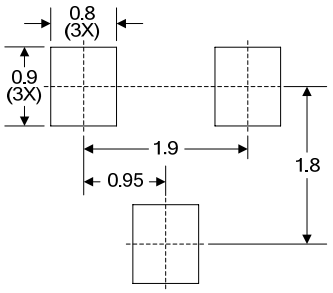
Dimensions (SOT-23)



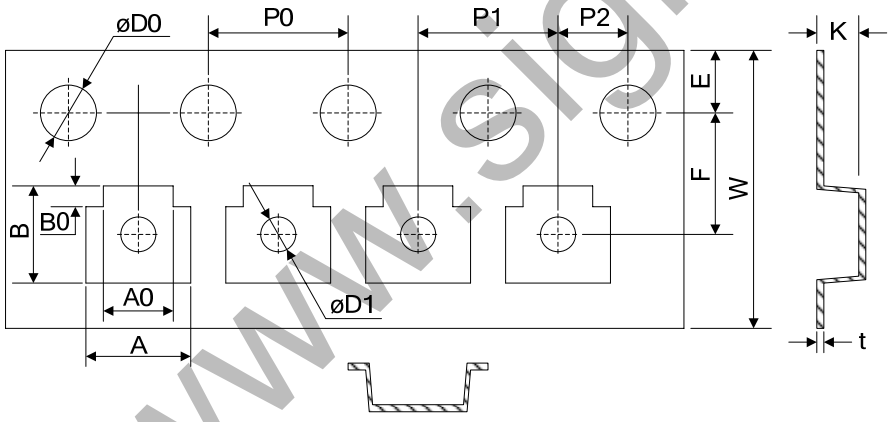


Recommended Soldering Pad Layout

Symbol	Dimension			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.08	0.18	0.003	0.007
B	0.15	-	0.006	-
C	-	0.13	-	0.005
D	0.89	1.09	0.035	0.043
E	2.80	3.05	0.110	0.120
F	1.90		0.075	
G	0.95		0.037	
H	1.19	1.40	0.047	0.055
I	2.10	2.49	0.083	0.098
J	0.35	0.50	0.014	0.020

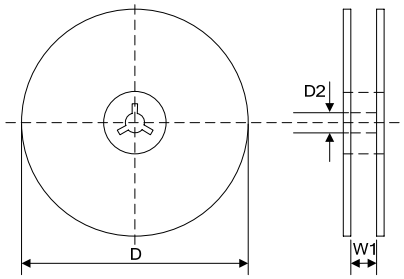
Packaging

Tape



Symbol	Dimension (mm)
W	8.00±0.30
P0	4.00±0.10
P1	4.00±0.10
P2	2.00±0.10
D0	Φ1.55±0.10
D1	Φ1.00±0.05
E	1.75±0.10
F	3.50±0.10
A	3.10±0.10
A0	2.10±0.10
B	2.75±0.10
B0	0.65±0.10
K	1.10±0.10
t	0.20±0.05

Reel



D	Φ178.0±2.0
D2	Φ13.0
W1	9.5
Quantity: 3000PCS	

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